

SOT1375-5

WLCSP4, wafer level chip-scale package, 4 terminals, 1.31 mm x 0.94 mm x 0.5 mm body

17 December 2018

Package information

1 Package summary

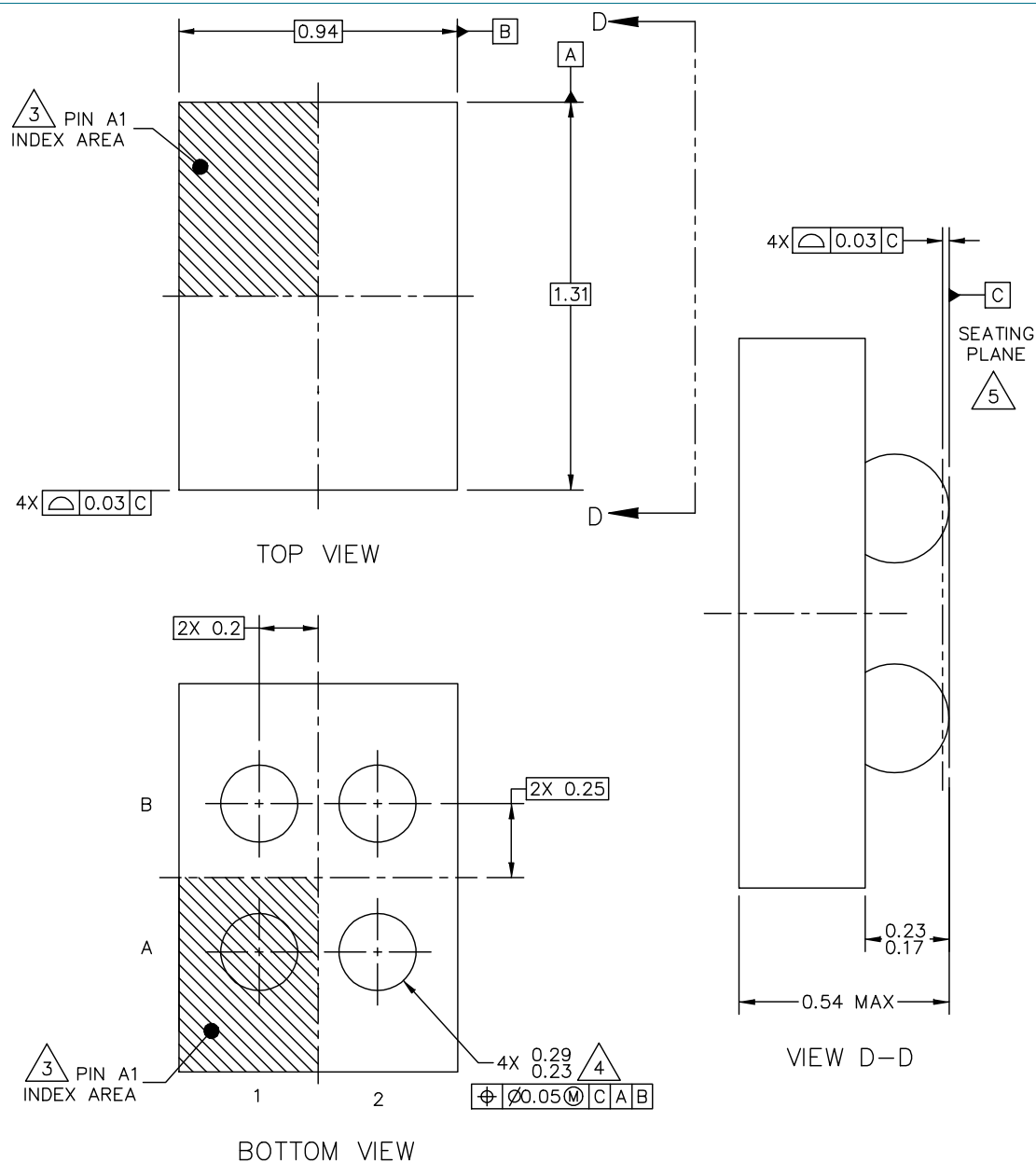
Terminal position code	B (bottom)
Package type descriptive code	WLCSP4
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	30-11-2018
Manufacturer package code	98ASA01358D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.31	-	mm
package width	-	0.94	-	mm
package height	-	0.5	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	4	-	



2 Package outline



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DATE: 30 NOV 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01358D	REVISION: 0
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Figure 1. Package outline WLCSP4 (SOT1375-5)

3 Soldering

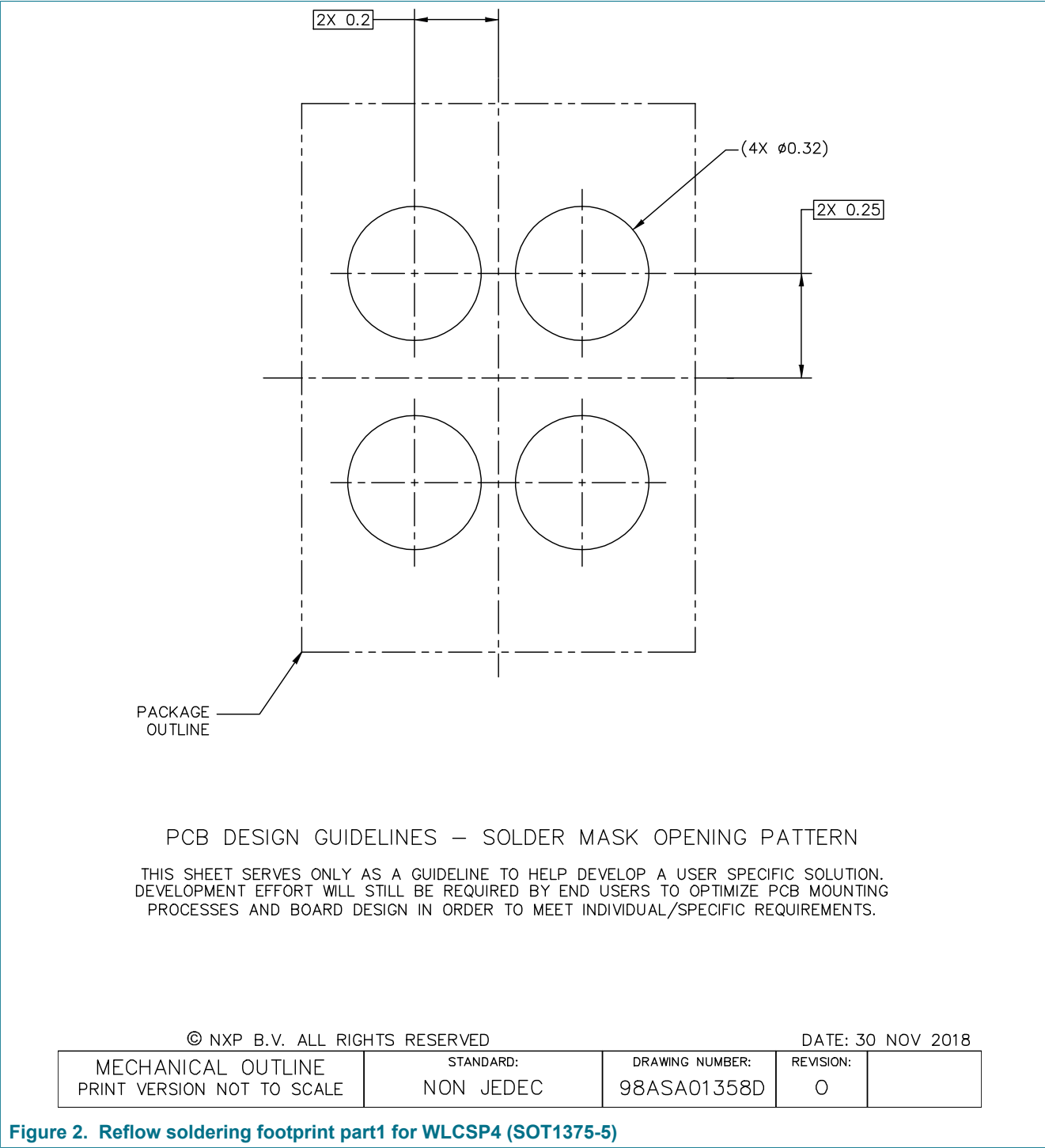


Figure 2. Reflow soldering footprint part1 for WLCSP4 (SOT1375-5)

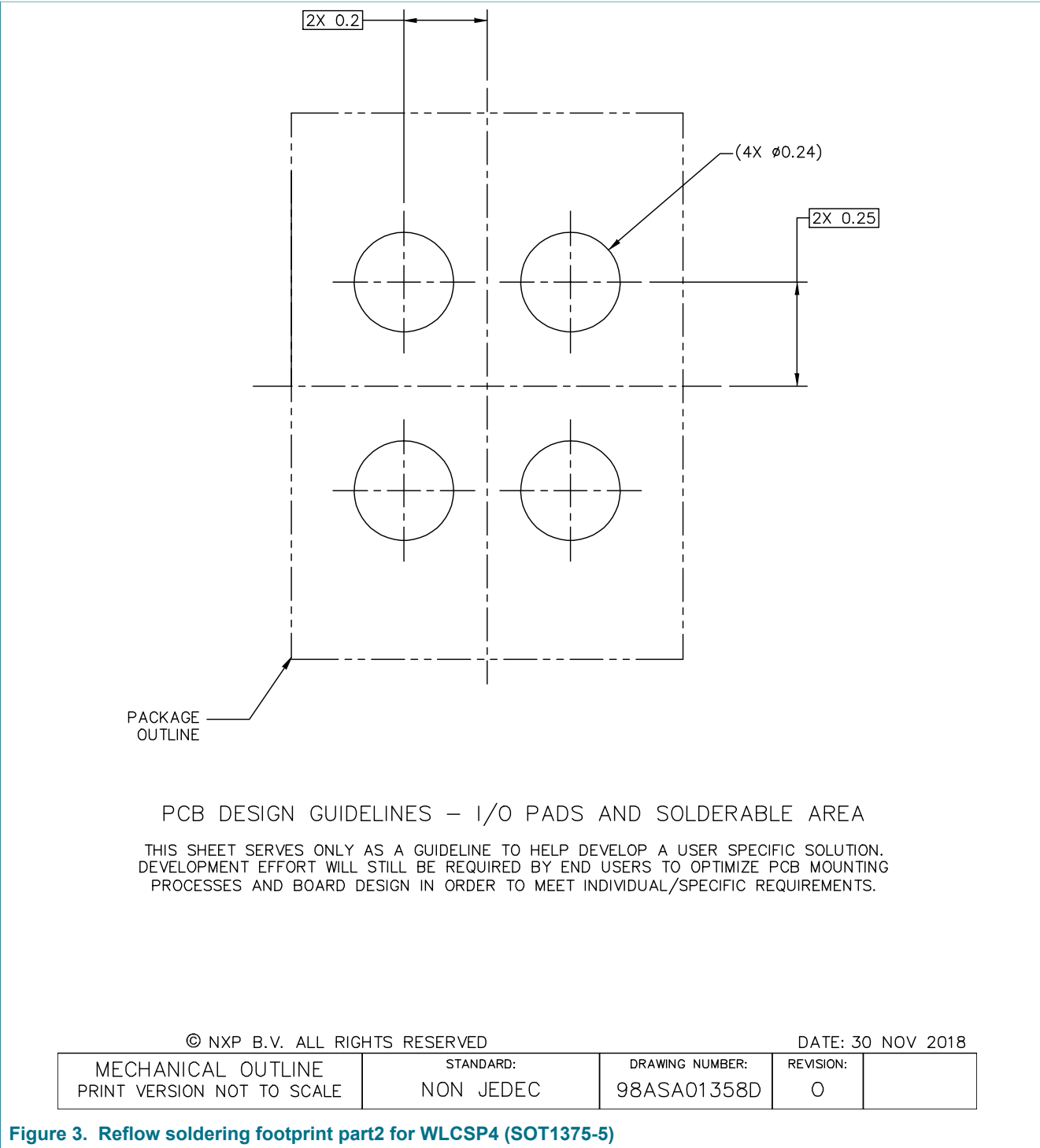
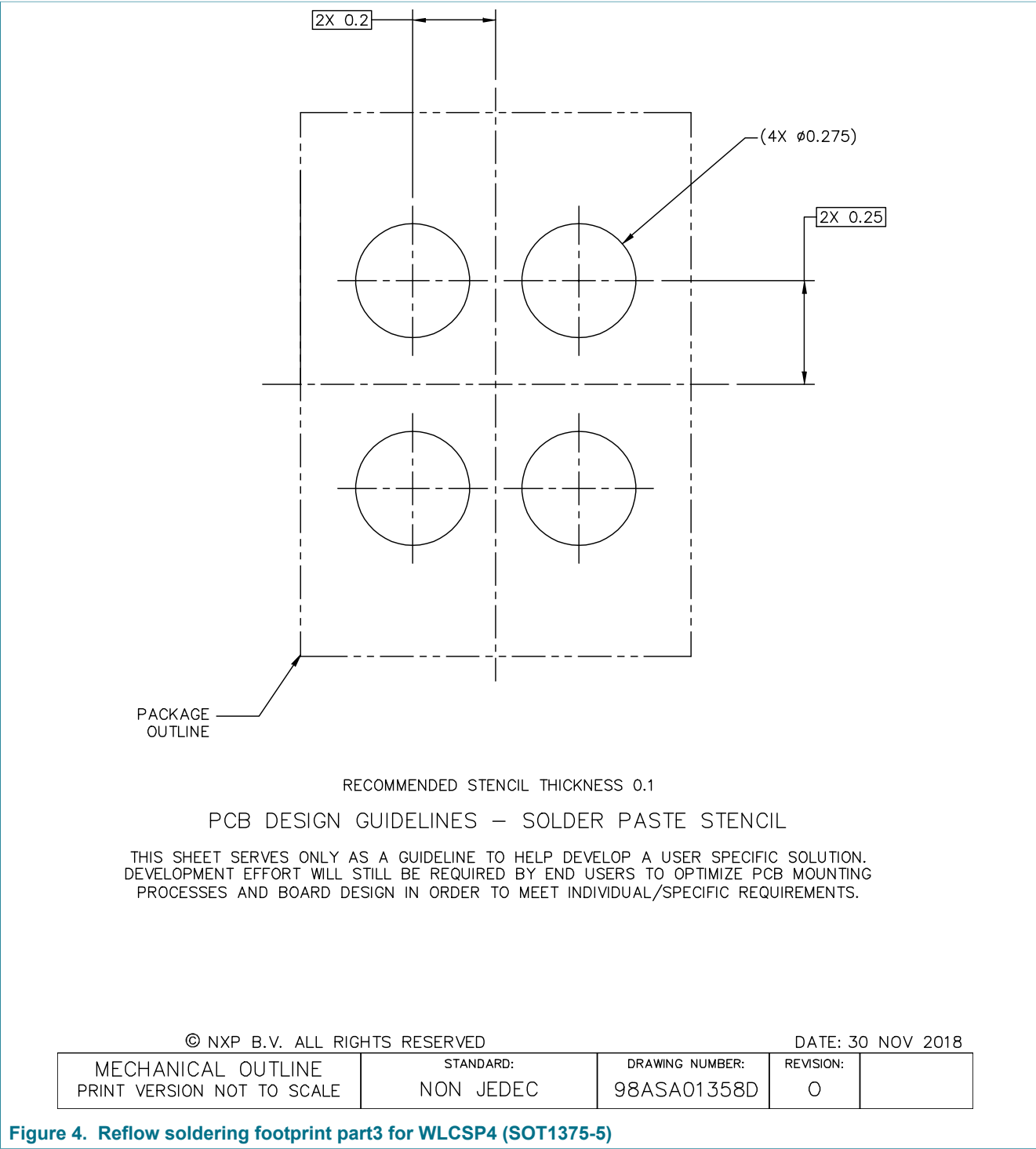


Figure 3. Reflow soldering footprint part2 for WLCSP4 (SOT1375-5)



WLCSP4, wafer level chip-scale package, 4 terminals, 1.31 mm x 0.94 mm x 0.5 mm body

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 - 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
 - 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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Figure 5. Package outline note WLCSP4 (SOT1375-5)

4 Legal information

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